ABSTRACT OF THE DISCLOSURE

A method of making an exposed-pad ball-grid array package (11) includes applying a conductive sheet (16) to an adhesive tape (18). Stamping the conductive sheet (16) to form a die pad (24) and separating the remainder (26) of the sheet from the adhesive tape (18) so that only the die pad (24) remains on the adhesive tape (18). A substrate (28) is applied to the adhesive tape (18) proximate to the die pad (24). A die (30) is attached to the die pad (24) and electrically coupled to the substrate (28). An encapsulant (34) is formed around at least a portion of the die (30), the die pad (24) and the substrate (28) above the adhesive tape (18). The adhesive tape (18) is removed from the die pad (24), substrate (28) and encapsulant (34). Conductive balls (36) are attached to the substrate (28).

[FIG. 11]